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DATA SHEET

74F148
8-input priority encoder

Product specification

1990 Mar 01

IC15 Data Handbook

Philips
Semiconductors

PHILIPS

8-input priority encoder 74F148

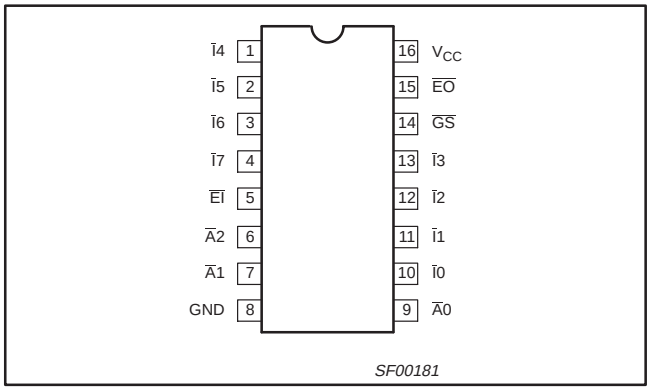
FEATURES

- Code conversions
- Multi-channel D/A converter
- Decimal-to-BCD converter
- Cascading for priority encoding of “N” bits
- Input enable capability
- Priority encoding-automatic selection of highest priority input line
- Output enable-active Low when all inputs are High
- Group signal output-active when any input is Low

DESCRIPTION

The 74F148 8-input priority encoder accepts data from eight active-Low inputs and provides a binary representation on the three active-Low outputs. A priority is assigned to each input so that when two or more inputs are simultaneously active, the input with the highest priority is represented on the output, with input line $\overline{I}7$ having the highest priority. A High on the Enable Input ($\overline{EI}$) will force all outputs to the inactive (High) state and allow new data to settle without producing erroneous information at the outputs. A Group Signal ($\overline{GS}$) output and an Enable Output ($\overline{EO}$) are provided with the three data outputs. The $\overline{GS}$ is active-Low when any input is Low: this indicates when any input is active. The $\overline{EO}$ is active-Low when all inputs are High. Using the Enable Output along with the Enable Input allows priority encoding of N input signals. Both $\overline{EO}$ and $\overline{GS}$ are active-High when the Enable Input is High.

PIN CONFIGURATION



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F148	6.0ns	23mA

ORDERING INFORMATION

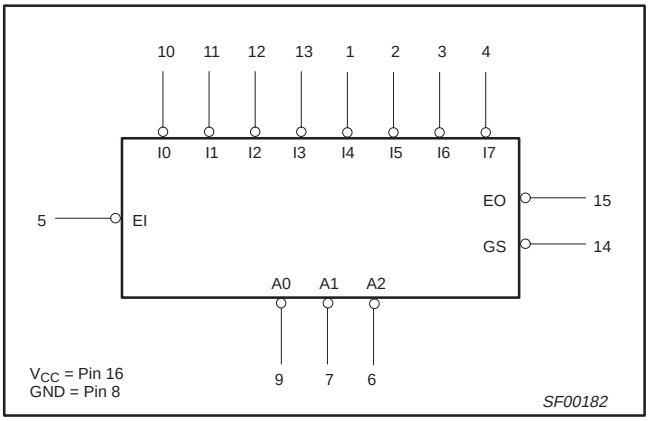
DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V ±10%, T_{amb} = 0°C to +70°C	PKG DWG #
16-pin plastic DIP	N74F148N	SOT38-4
16-pin plastic SO	N74F148D	SOT109-1

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

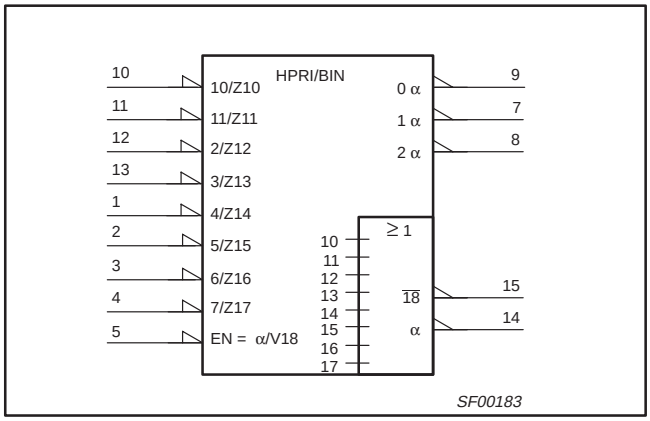
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
$\overline{I}1$ – $\overline{I}7$	Priority inputs (active Low)	1.0/2.0	20µA/1.2mA
$\overline{I}0$	Priority input (active Low)	1.0/1.0	20µA/0.6mA
$\overline{EI}$	Enable input (active Low)	1.0/2.0	20µA/1.2mA
$\overline{EO}$	Enable output (active Low)	50/33	1.0mA/20mA
$\overline{GS}$	Group select output (active Low)	50/33	1.0mA/20mA
$\overline{A}0$ – $\overline{A}2$	Address outputs (active Low)	50/33	1.0mA/20mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

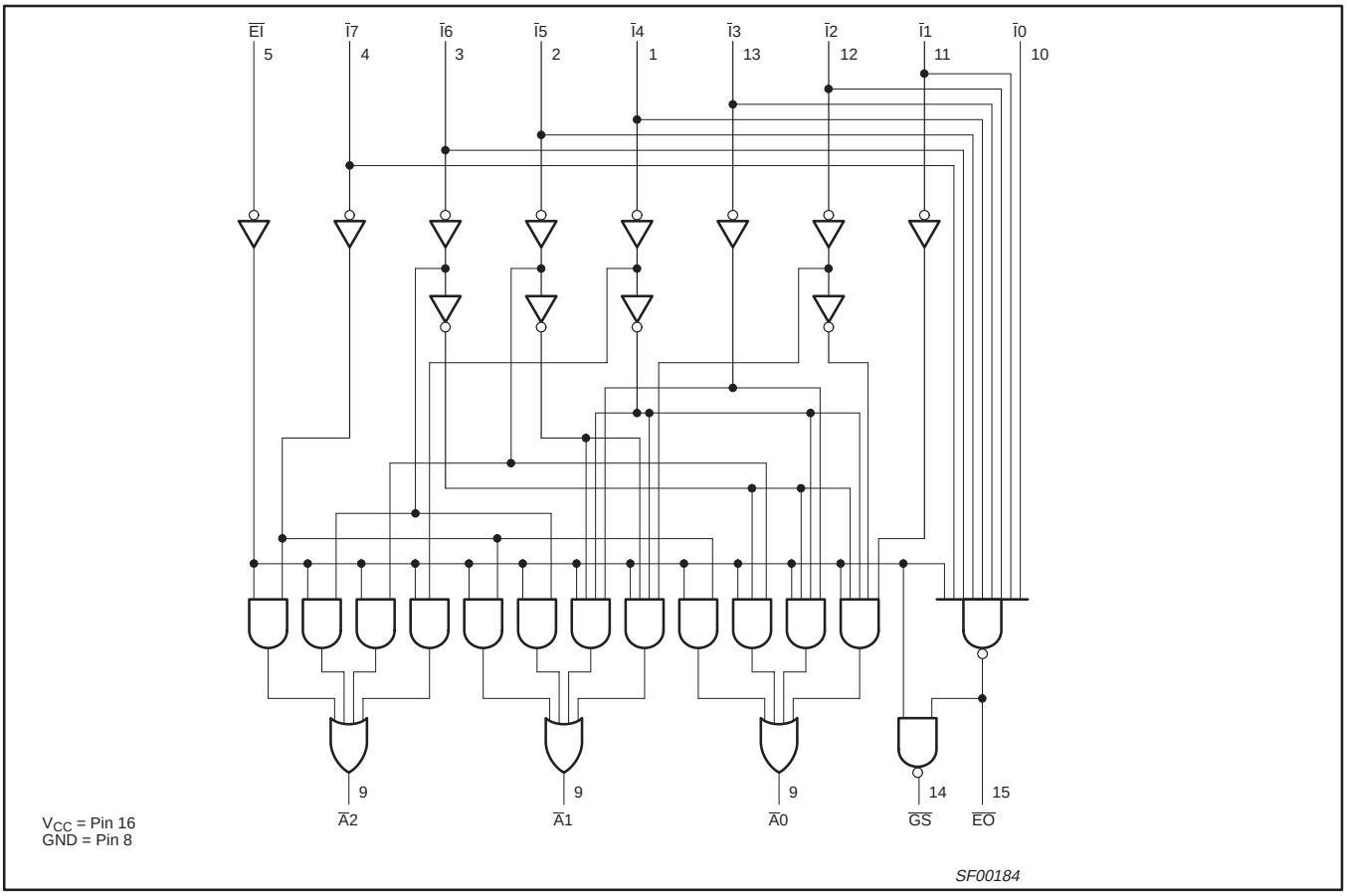
LOGIC SYMBOL



IEC/IEEE SYMBOL



LOGIC DIAGRAM

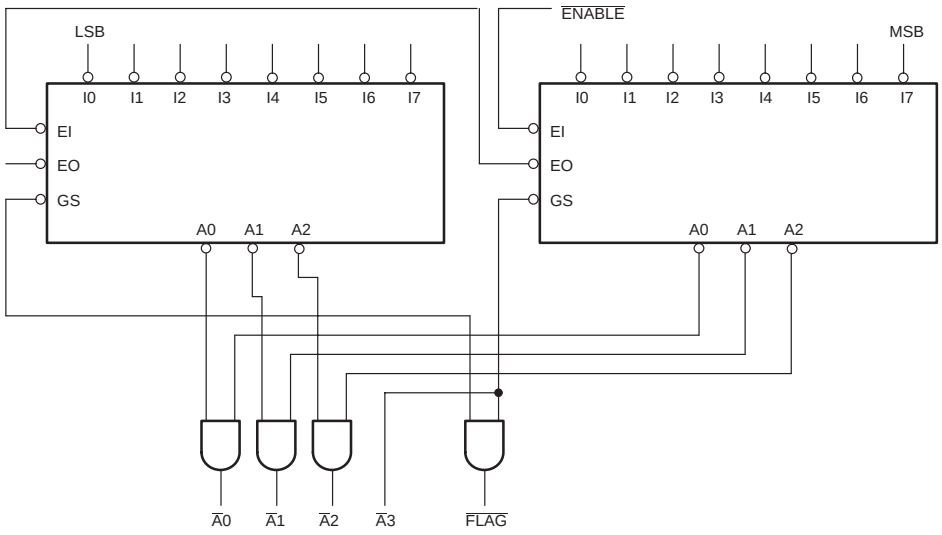


FUNCTION TABLE

INPUTS									OUTPUTS				
$\overline{EI}$	$\overline{I0}$	$\overline{I1}$	$\overline{I2}$	$\overline{I3}$	$\overline{I4}$	$\overline{I5}$	$\overline{I6}$	$\overline{I7}$	$\overline{GS}$	$\overline{A0}$	$\overline{A1}$	$\overline{A2}$	$\overline{EO}$
H	X	X	X	X	X	X	X	X	H	H	H	H	H
L	H	H	H	H	H	H	H	H	H	H	H	H	L
L	X	X	X	X	X	X	X	L	L	L	L	L	H
L	X	X	X	X	X	X	L	H	L	H	L	L	H
L	X	X	X	X	X	L	H	H	L	L	H	L	H
L	X	X	X	X	L	H	H	H	L	H	H	L	H
L	X	X	X	L	H	H	H	H	L	L	L	H	H
L	X	X	L	H	H	H	H	H	L	H	L	H	H
L	X	L	H	H	H	H	H	H	L	L	H	H	H
L	L	H	H	H	H	H	H	H	L	H	H	H	H

H = High voltage level
L = Low voltage level
X = Don't care

APPLICATION



16-Input Priority Encoder

SF00185

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device.
Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	–0.5 to +7.0	V
V_{IN}	Input voltage	–0.5 to +7.0	V
I_{IN}	Input current	–30 to +5	mA
V_{OUT}	Voltage applied to output in High output state	–0.5 to V_{CC}	V
I_{OUT}	Current applied to output in Low output state	40	mA
T_{amb}	Operating free-air temperature range	0 to +70	°C
T_{stg}	Storage temperature range	–65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			–18	mA
I_{OH}	High-level output current			–1	mA
I_{OL}	Low-level output current			20	mA
T_{amb}	Operating free-air temperature range	0		+70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIONS[1]		LIMITS			UNIT
					MIN	TYP[2]	MAX	
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IL} = MAX	±10%V_{CC}	2.5			V
			V_{IH} = MIN, I_{OH} = MAX	±5%V_{CC}	2.7	3.4		
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IL} = MAX	±10%V_{CC}		0.30	0.50	V
			V_{IH} = MIN, I_{OL} = MAX	±5%V_{CC}		0.30	0.50	
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = I_{IK}			–0.73	–1.2	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 7.0V				100	µA
I_{IH}	High-level input current		V_{CC} = MAX, V_I = 2.7V				20	µA
I_{IL}	Low-level input current	$\overline{I0}$	V_{CC} = MAX, V_I = 0.5V				–0.6	mA
		$\overline{I1}$ – $\overline{I7}$, $\overline{EI}$					–1.2	mA
I_{OS}	Short-circuit output current[3]		V_{CC} = MAX		–60		–150	mA
I_{CC}	Supply current (total)[4]		V_{CC} = MAX			23	35	mA

NOTES:

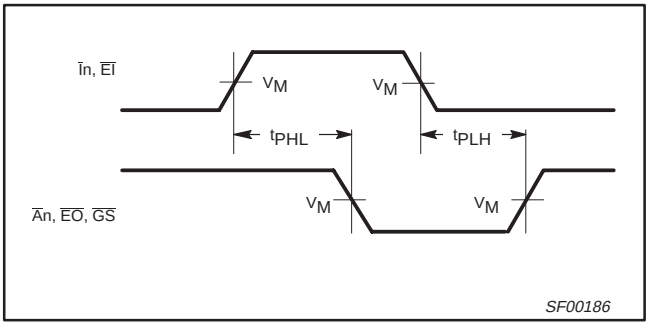
1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
2. All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
4. To measure I_{CC}, outputs must be open, V_{IN} on all inputs = 4.5V.

AC ELECTRICAL CHARACTERISTICS

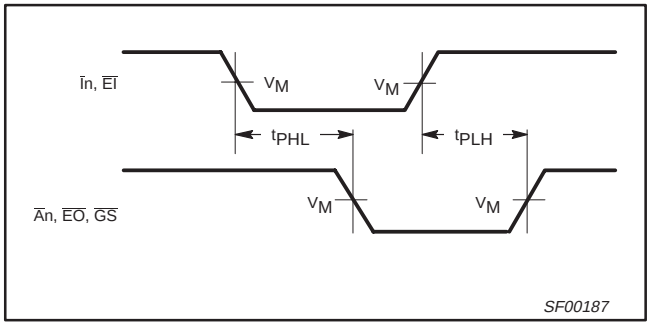
SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			V_{CC} = +5.0V T_{amb} = +25°C C_L = 50pF, R_L = 500Ω			V_{CC} = +5.0V ± 10% T_{amb} = 0°C to +70°C C_L = 50pF, R_L = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
t_{PLH} t_{PHL}	Propagation delay $\overline{In}$ to $\overline{An}$	Waveform 2	3.5 3.5	6.0 6.0	9.0 9.0	3.5 3.5	10.0 10.0	ns
t_{PLH} t_{PHL}	Propagation delay $\overline{In}$ to $\overline{EO}$	Waveform 1	1.5 1.5	3.0 2.5	6.5 6.5	1.5 1.5	7.5 7.5	ns
t_{PLH} t_{PHL}	Propagation delay $\overline{In}$ to $\overline{GS}$	Waveform 2	2.0 2.0	4.0 4.0	8.0 8.0	2.0 2.0	9.0 9.0	ns
t_{PLH} t_{PHL}	Propagation delay $\overline{EI}$ to $\overline{An}$	Waveform 2	3.5 3.0	6.0 5.5	8.5 8.0	3.5 3.0	9.5 9.0	ns
t_{PLH} t_{PHL}	Propagation delay $\overline{EI}$ to $\overline{GS}$	Waveform 2	2.5 3.0	4.5 5.5	7.0 7.5	2.5 3.0	8.0 8.5	ns
t_{PLH} t_{PHL}	Propagation delay $\overline{EI}$ to $\overline{EO}$	Waveform 2	3.0 3.5	5.0 5.0	7.0 7.5	3.0 3.5	8.0 9.0	ns

AC WAVEFORMS

For all waveforms, V_M = 1.5V.

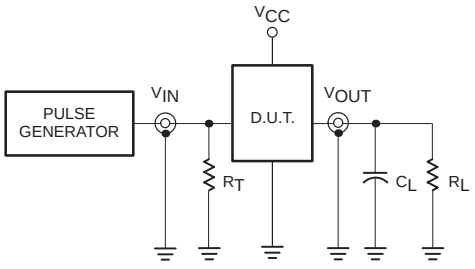


Waveform 1. For Inverting Outputs

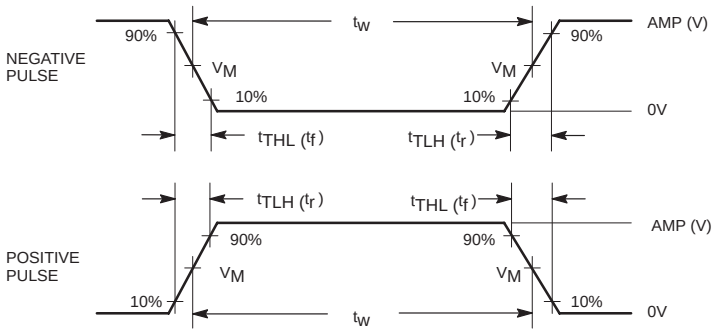


Waveform 2. For Non-Inverting Outputs

TEST CIRCUIT AND WAVEFORMS



Test Circuit for Totem-Pole Outputs



DEFINITIONS:

R_L = Load resistor;
see AC ELECTRICAL CHARACTERISTICS for value.

C_L = Load capacitance includes jig and probe capacitance;
see AC ELECTRICAL CHARACTERISTICS for value.

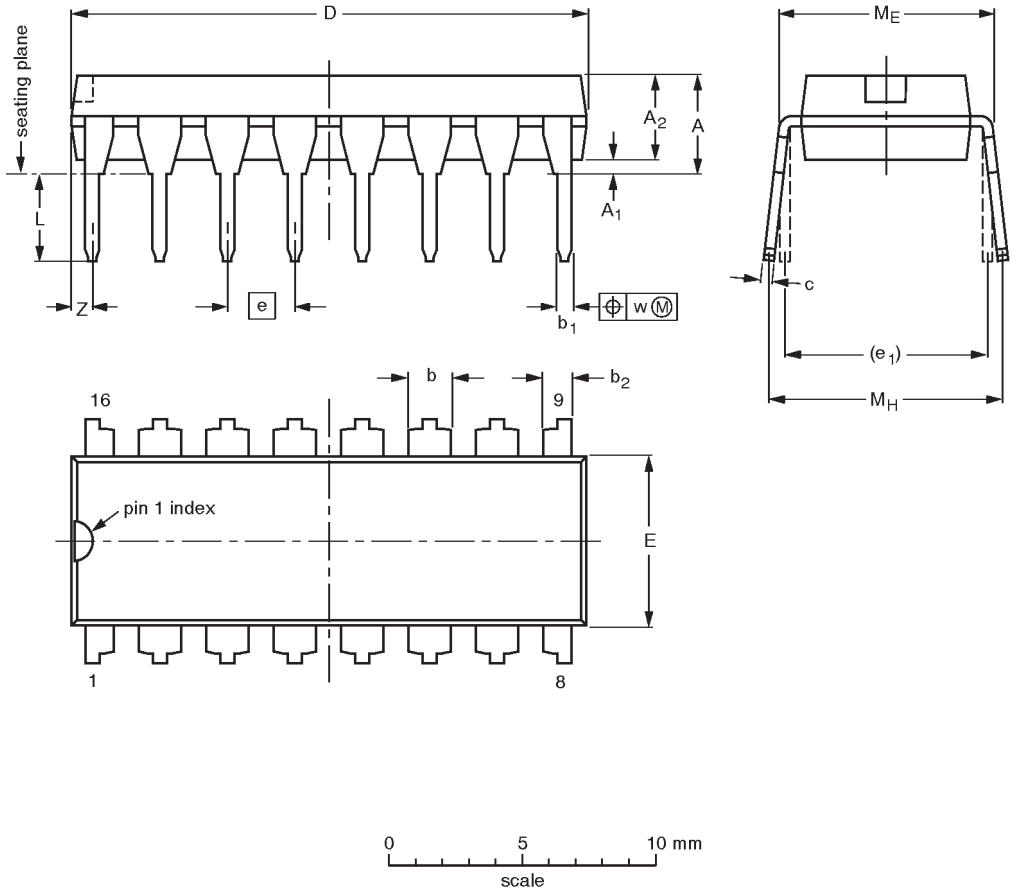
R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

Input Pulse Definition

family	INPUT PULSE REQUIREMENTS					
	amplitude	V_M	rep. rate	t_w	t_{TLH}	t_{THL}
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

SF00006

DIP16: plastic dual in-line package; 16 leads (300 mil) **SOT38-4**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

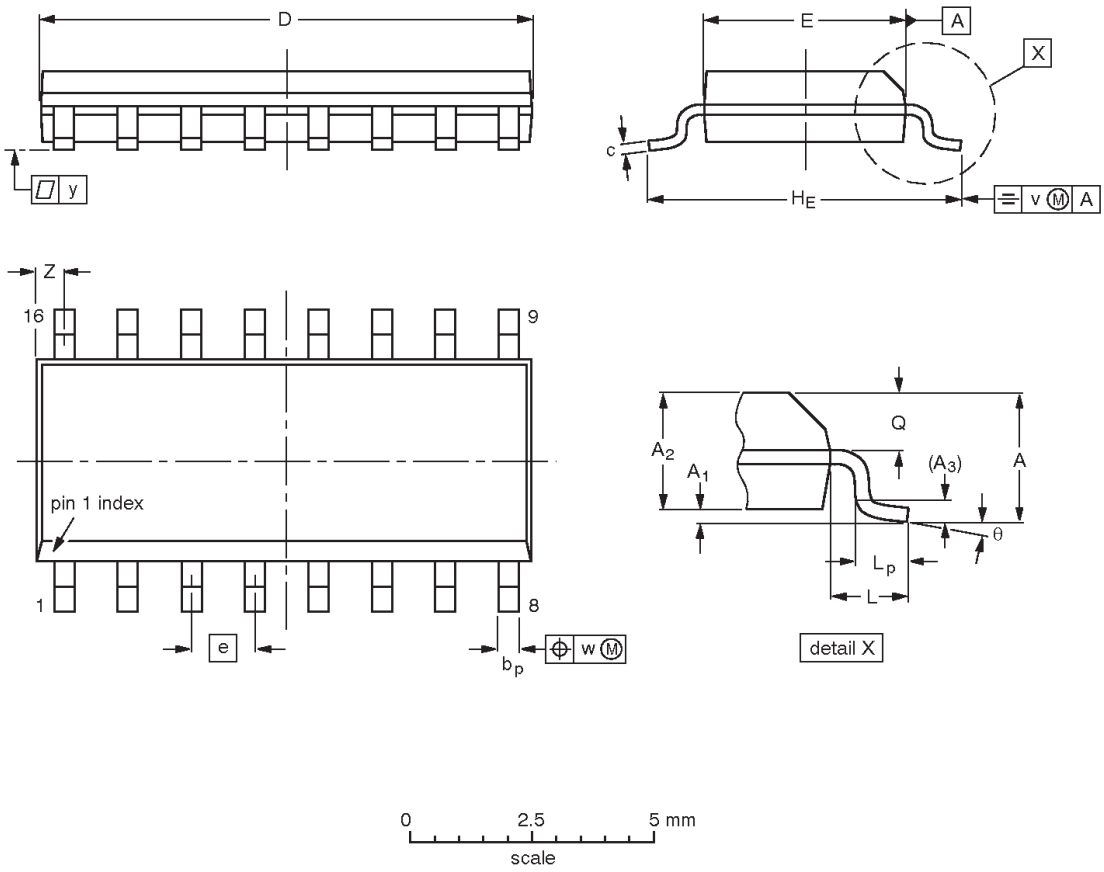
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	b_2	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-4						~~92-11-17~~ 95-01-14

SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				~~95-01-23~~ 97-05-22

NOTES

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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